

Power Management Switch ICs for PCs and Digital Consumer Products

2ch High Side Switch ICs for USB Devices and Memory Cards



BD2062FJ, BD2066FJ

No.11029EBT15

●Description

High side switch for USB is a high side switch having over-current protection used in power supply line of universal serial bus (USB). Its switch unit has two channels of N-channel power MOSFET. And, over-current detection circuit, thermal shutdown circuit, under-voltage lockout and soft-start circuit are built in.

●Features

- 1) Dual N-MOS High Side Switch
- 2) Current Limit Threshold 2.4A
- 3) Control Input Logic
 - Active-Low : BD2062FJ
 - Active-High : BD2066FJ
- 4) Soft-Start Circuit
- 5) Over-Current Detection
- 6) Thermal Shutdown
- 7) Under-Voltage Lockout
- 8) Open-Drain Error Flag Output
- 9) Reverse Current Protection When Switch Off
- 10) Flag Output Delay Filter Built In
- 11) Power Supply Voltage Range 2.7V~5.5V
- 12) TTL Enable Input
- 13) 0.8ms Typical Rise Time
- 14) 1μA Max Standby Current

●Applications

PC, PC peripheral USB hub in consumer appliances, Car accessory, and so forth

●Line Up Matrix

Parameter	BD2062FJ	BD2066FJ
Current limit threshold (A)	2.4	2.4
Control input logic	Low	High
Number of channels	2ch	2ch
Package	SOP-J8	SOP-J8

●Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Supply voltage	V _{IN}	-0.3 ~ 6.0	V
Enable input voltage	V _{EN}	-0.3 ~ 6.0	V
/OC voltage	V/ _{OC}	-0.3 ~ 6.0	V
/OC sink current	I _{S/OC}	~ 5	mA
OUT voltage	V _{OUT}	-0.3 ~ 6.0	V
Storage temperature	T _{STG}	-55 ~ 150	°C
Power dissipation	P _d	675 ^{*1}	mW

^{*1} Mounted on 70mm * 70mm * 1.6mm glass-epoxy PCB. Derating : 5.4mW/°C above Ta=25°C

* This product is not designed for protection against radioactive rays.

●Operating Conditions

Parameter	Symbol	Ratings			Unit
		Min.	Typ.	Max.	
Operating voltage	V _{IN}	2.7	-	5.5	V
Operating temperature	T _{OPR}	-40	-	85	°C

●Electrical Characteristics

 OBD2062FJ (Unless otherwise specified $V_{IN} = 5.0V$, $T_a = 25^{\circ}C$)

Parameter	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
Operating current	I_{DD}	-	130	180	μA	$V_{EN} = 0V$, $OUT=OPEN$
Standby current	I_{STB}	-	0.01	1	μA	$V_{EN} = 5V$, $OUT=OPEN$
/EN input voltage	V_{EN}	2.0	-	-	V	High input
	V_{EN}	-	-	0.8	V	Low input
/EN input current	I_{EN}	-1.0	0.01	1.0	μA	$V_{EN} = 0V$ or $V_{EN} = 5V$
/OC output low voltage	V_{OCL}	-	-	0.5	V	$I_{OC} = 1mA$
/OC output leak current	$I_{L/OC}$	-	0.01	1	μA	$V_{OC} = 5V$
/OC delay time	T_{OC}	10	15	20	ms	
On-resistance	R_{ON}	-	80	125	$m\Omega$	$I_{OUT} = 500mA$
Switch leak current	I_{LSW}	-	-	1.0	μA	$V_{EN} = 5V$, $V_{OUT} = 0V$
Reverse leak current	I_{LREV}	-	-	1.0	μA	$V_{OUT} = 5.5V$, $V_{IN} = 0V$
Current limit threshold	I_{TH}	1.5	2.4	3.0	A	
Short circuit current	I_{SC}	1.1	1.5	2.1	A	$V_{OUT} = 0V$ $C_L = 47\mu F$ (RMS)
Output rise time	T_{ON1}	-	0.8	10	ms	$R_L = 10\Omega$
Output turn-on time	T_{ON2}	-	1.1	20	ms	$R_L = 10\Omega$
Output fall time	T_{OFF1}	-	5	20	μs	$R_L = 10\Omega$
Output turn-off time	T_{OFF2}	-	10	40	μs	$R_L = 10\Omega$
UVLO threshold	V_{TUVH}	2.1	2.3	2.5	V	Increasing V_{IN}
	V_{TUVL}	2.0	2.2	2.4	V	Decreasing V_{IN}

OBD2066FJ (Unless otherwise specified VIN = 5.0V, Ta = 25 °C)

Parameter	Symbol	Limits			Unit	Condition
		Min.	Typ.	Max.		
Operating current	IDD	-	130	180	μA	VEN = 5V , OUT=OPEN
Standby current	ISTB	-	0.01	1	μA	VEN = 0V , OUT=OPEN
EN input voltage	VEN	2.0	-	-	V	High input
	VEN	-	-	0.8	V	Low input
EN input current	IEN	-1.0	0.01	1.0	μA	VEN = 0V or VEN = 5V
/OC output low voltage	V/OCL	-	-	0.5	V	I/OC = 1mA
/OC output leak current	IL/OC	-	0.01	1	μA	V/OC = 5V
/OC delay time	T/OC	10	15	20	ms	
On-resistance	RON	-	80	125	mΩ	IOUT = 500mA
Switch leak current	ILSW	-	-	1.0	μA	VEN = 0V, VOUT = 0V
Reverse leak current	ILREV	-	-	1.0	μA	VOUT = 5.5V, VIN = 0V
Current limit threshold	ITH	1.5	2.4	3.0	A	
Short circuit current	ISC	1.1	1.5	2.1	A	VOUT = 0V CL = 47μF (RMS)
Output rise time	TON1	-	0.8	10	ms	RL = 10Ω
Output turn-on time	TON2	-	1.1	20	ms	RL = 10Ω
Output fall time	TOFF1	-	5	20	μs	RL = 10Ω
Output turn-off time	TOFF2	-	10	40	μs	RL = 10Ω
UVLO threshold	VTUVH	2.1	2.3	2.5	V	Increasing VIN
	VTUVL	2.0	2.2	2.4	V	Decreasing VIN

●Measurement Circuit

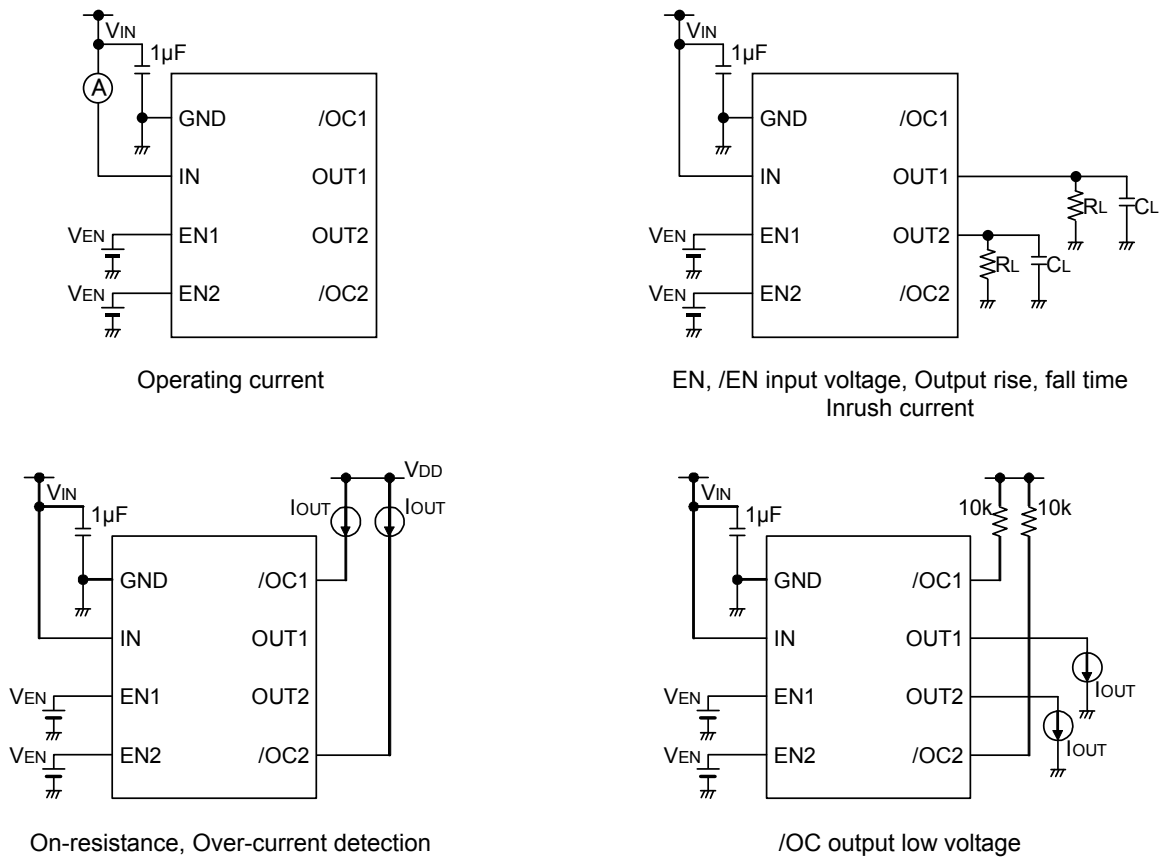


Fig.1 Measurement circuit

●Timing Diagram

OBD2062FJ

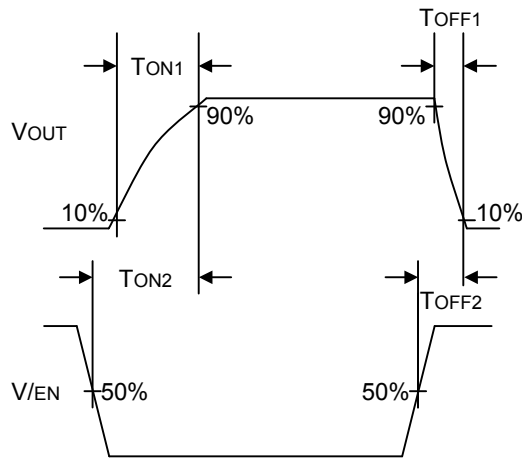


Fig.2 Timing diagram

OBD2066FJ

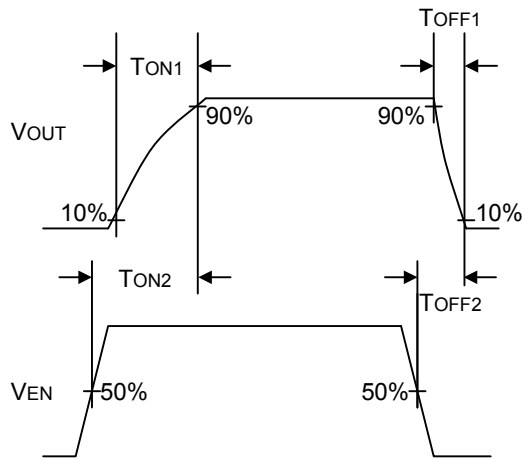


Fig.3 Timing diagram

●Electrical Characteristic Curves (Reference Data)

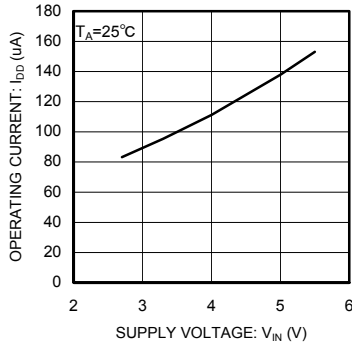
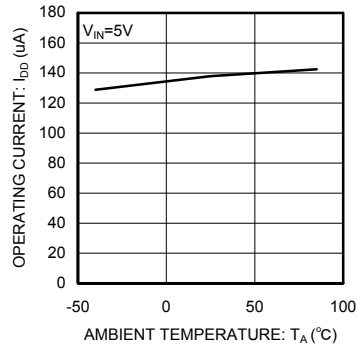
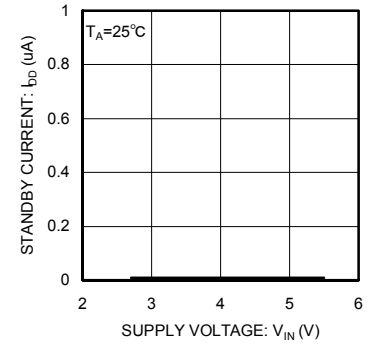
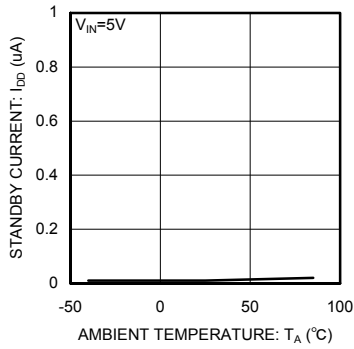
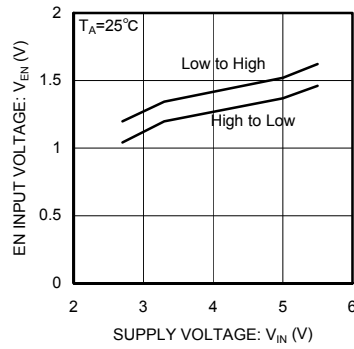
Fig.4 Operating current
EN, /EN enableFig.5 Operating current
EN, /EN enableFig.6 Standby current
EN, /EN disableFig.7 Standby current
EN, /EN disable

Fig.8 EN, /EN input voltage

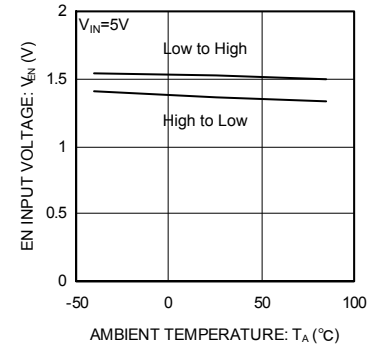


Fig.9 EN, /EN input voltage

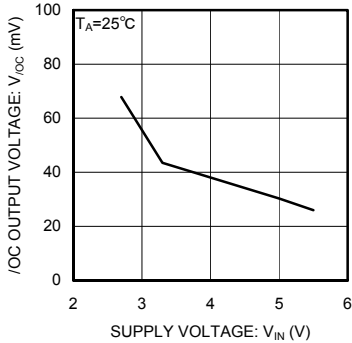


Fig.10 /OC output low voltage

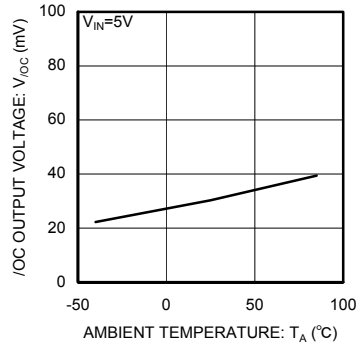


Fig.11 /OC output low voltage

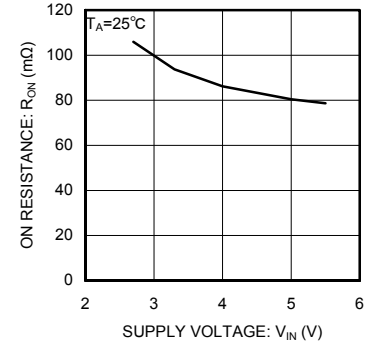


Fig.12 On-resistance

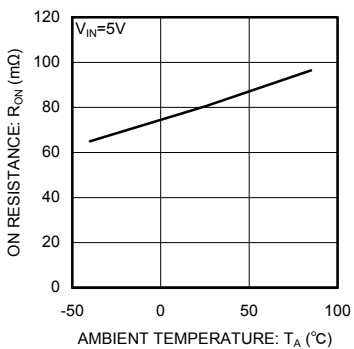


Fig.13 On-resistance

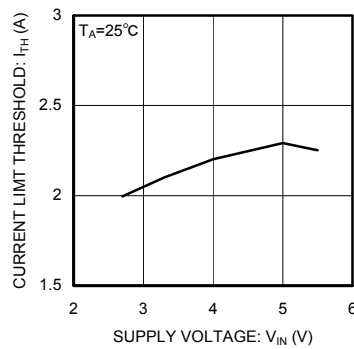


Fig.14 Current limit threshold

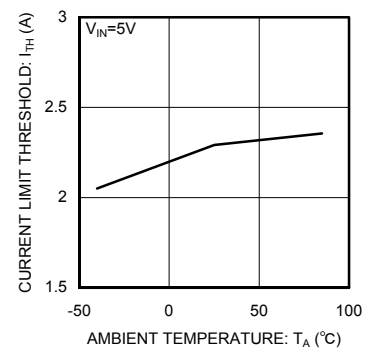


Fig.15 Current limit threshold

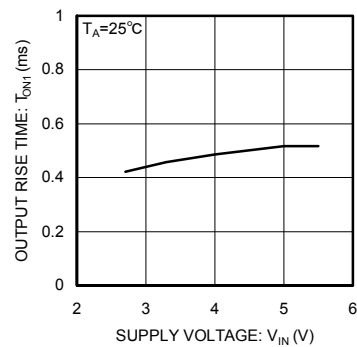


Fig.16 Short circuit current

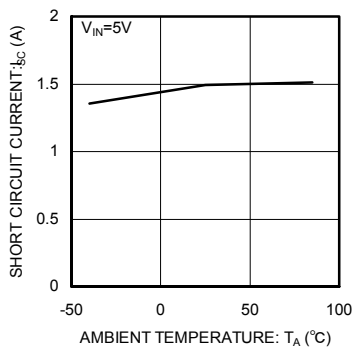


Fig.17 Short circuit current

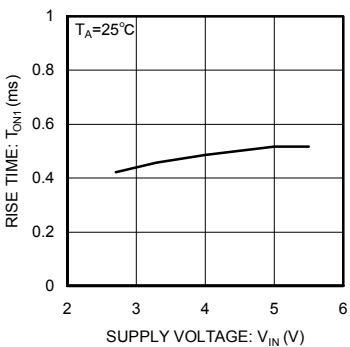


Fig.18 Output rise time

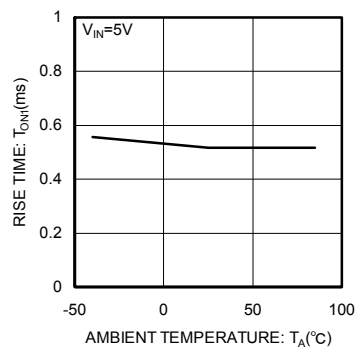


Fig.19 Output rise time

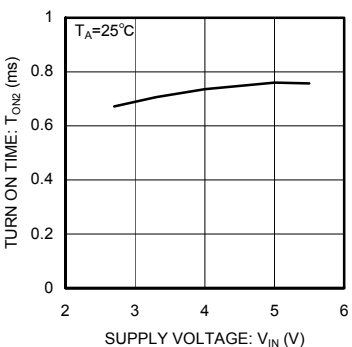


Fig.20 Output turn-on time

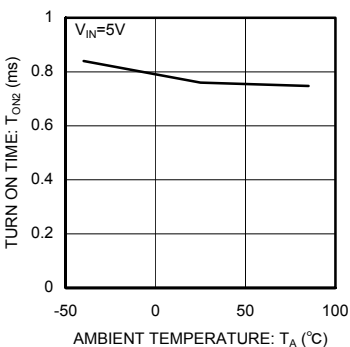


Fig.21 Output turn-on time

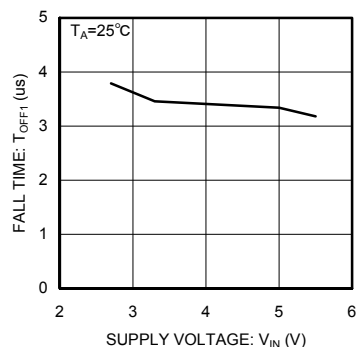


Fig.22 Output fall time

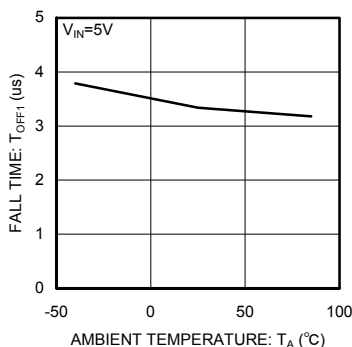


Fig.23 Output fall time

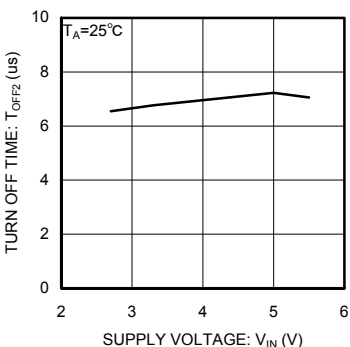


Fig.24 Output turn-off time

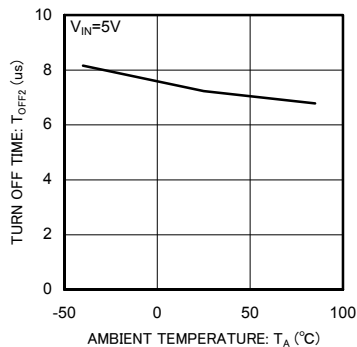


Fig.25 Output turn-off time

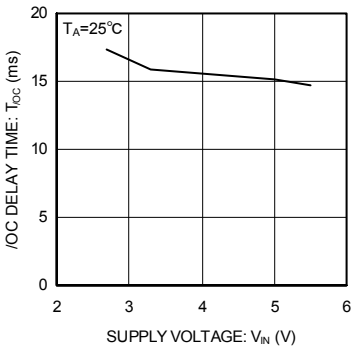


Fig.26 /OC delay time

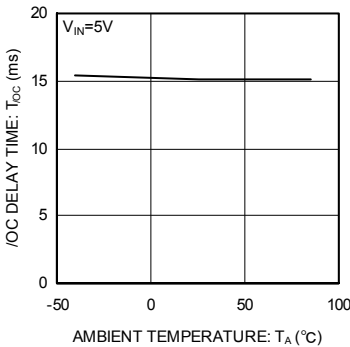


Fig.27 /OC delay time

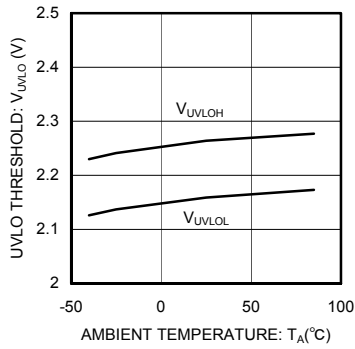


Fig.28 UVLO threshold voltage

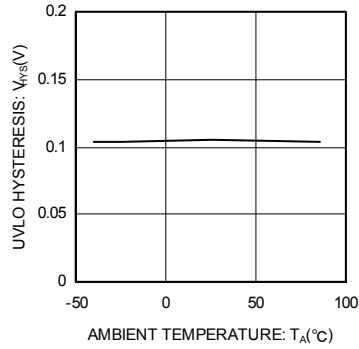


Fig.29 UVLO hysteresis voltage

●Waveform Data(BD2062FJ)

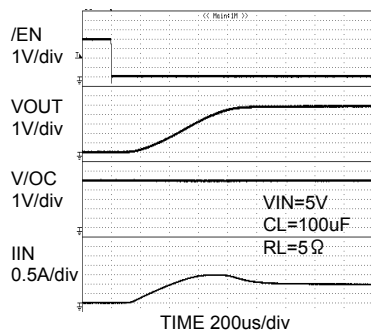


Fig.30 Output rise characteristics

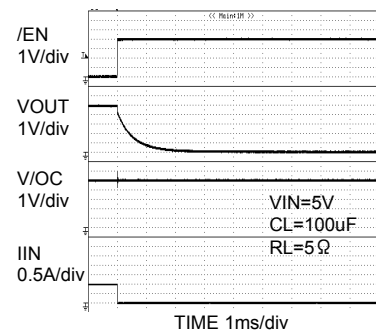


Fig.31 Output fall characteristics

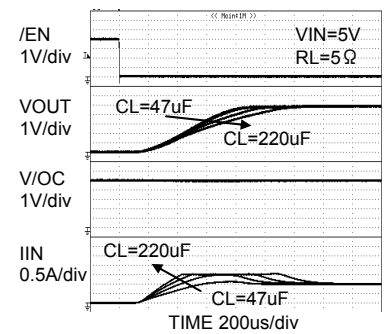
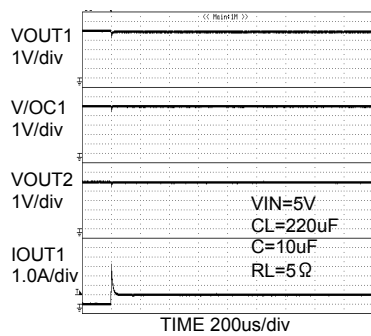
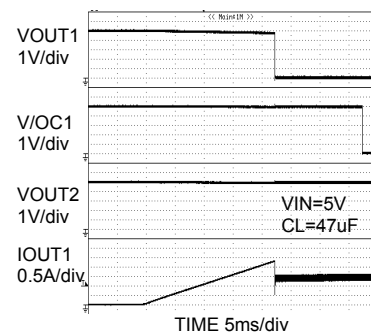
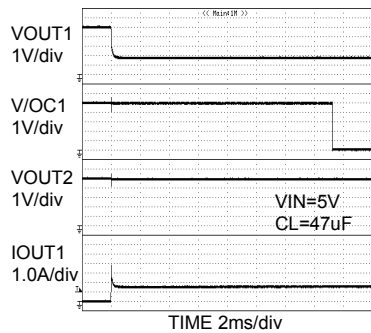
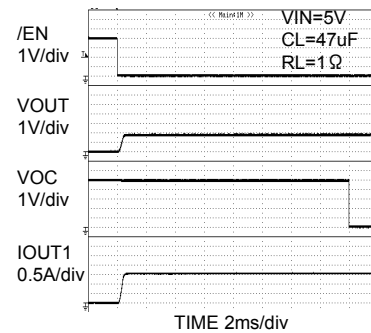
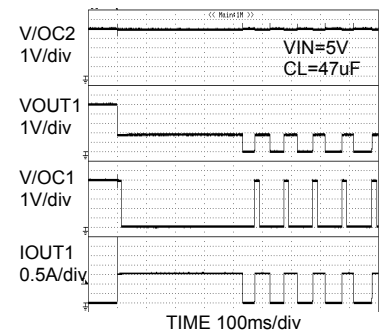
Fig.32 Inrush current
 $\text{CL}=47\mu\text{F}$, $100\mu\text{F}$, $147\mu\text{F}$, $220\mu\text{F}$ 

Fig.33 Inrush current

Fig.34 Over-current response
ramped loadFig.35 Over-current response
1 Ω load connected at enableFig.36 Over-current response
enable to short circuitFig.37 Thermal shutdown
response

●Block Diagram

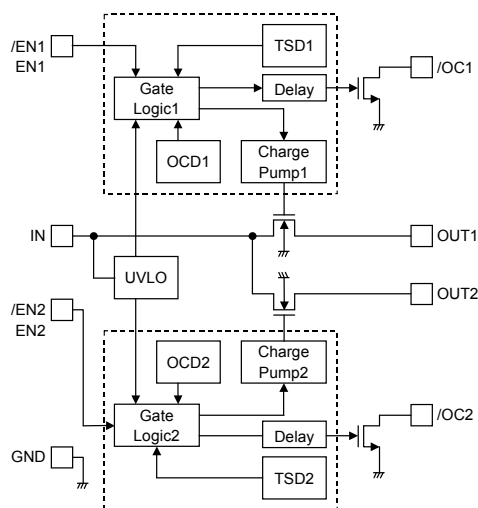


Fig.38 Block diagram

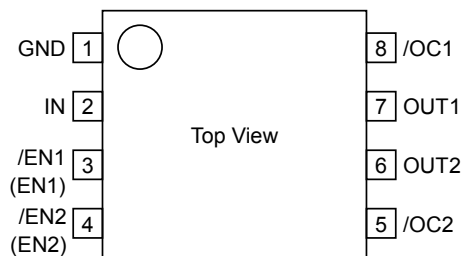


Fig.39 Pin configuration

●Pin Description

OBD2062FJ

Pin No.	Symbol	I / O	Pin function
1	GND	-	Ground.
2	IN	-	Power supply input. Input terminal to the switch and power supply input terminal of the internal circuit.
3, 4	/EN	I	Enable input. Switch on at Low level. High level input > 2.0V, Low level input < 0.8V.
5, 8	/OC	O	Error flag output. Low at over-current, thermal shutdown. Open drain output.
6, 7	OUT	O	Switch output.

OBD2066FJ

Pin No.	Symbol	I / O	Pin function
1	GND	-	Ground.
2	IN	-	Power supply input. Input terminal to the switch and power supply input terminal of the internal circuit.
3, 4	EN	I	Enable input. Switch on at High level. High level input > 2.0V, Low level input < 0.8V
5, 8	/OC	O	Error flag output. Low at over-current, thermal shutdown. Open drain output.
6, 7	OUT	O	Switch output.

● I/O Circuit

Symbol	Pin No	Equivalent circuit
EN1(/EN1) EN2(/EN2)	3, 4	
/OC1 /OC2	5, 8	
OUT1 OUT2	6, 7	

●Functional Description**1. Switch operation**

IN terminal and OUT terminal are connected to the drain and the source of switch MOSFET respectively. And the IN terminal is used also as power source input to internal control circuit.

When the switch is turned on from EN/EN control input, IN terminal and OUT terminal are connected by a 100mΩ switch. In on status, the switch is bidirectional. Therefore, when the potential of OUT terminal is higher than that of IN terminal, current flows from OUT terminal to IN terminal.

Since a parasitic diode between the drain and the source of switch MOSFET is canceled, in the off status, it is possible to prevent current from flowing reversely from OUT to IN.

2. Thermal shutdown circuit (TSD)

Thermal shut down circuit have dual thermal shutdown threshold. Since thermal shutdown works at a lower junction temperature when an over-current occurs, only the switch of an over-current state become off and error flag is output. Thermal shut down action has hysteresis. Therefore, when the junction temperature goes down, switch on and error flag output automatically recover. However, until cause of junction temperature increase such as output shortcircuit is removed or the switch is turned off, thermal shut down detection and recovery are repeated. The thermal shut down circuit works when the switch of either OUT1 or OUT2 is on (EN,/EN signal is active).

3. Over-current detection (OCD)

The over-current detection circuit limits current (ISC) and outputs error flag (/OC) when current flowing in each switch MOSFET exceeds a specified value. There are three types of response against over-current. The over-current detection circuit works when the switch is on (EN,/EN signal is active).

3-1. When the switch is turned on while the output is in short-circuit status

When the switch is turned on while the output is in short-circuit status or so, the switch gets in current limit status soon.

3-2. When the output short-circuits while the switch is on

When the output short-circuits or large capacity is connected while the switch is on, very large current flows until the over-current limit circuit reacts. When the current detection, limit circuit works, current limitation is carried out.

3-3. When the output current increases gradually

When the output current increases gradually, current limitation does not work until the output current exceeds the over-current detection value. When it exceeds the detection value, current limitation is carried out.

4. Under-voltage lockout (UVLO)

UVLO circuit prevents the switch from turning on until the VIN exceeds 2.3V(Typ.). If the VIN drops below 2.2V(Typ.) while the switch turns on, then UVLO shuts off the switch. UVLO has hysteresis of a 100mV(Typ.).

Under-voltage lockout circuit works when the switch of either OUT1 or OUT2 is on (EN,/EN signal is active).

5. Error flag (/OC) output

Error flag output is N-MOS open drain output. At detection of over-current, thermal shutdown, low level is output.

Over-current detection has delay filter. This delay filter prevents instantaneous current detection such as inrush current at switch on, hot plug from being informed to outside.

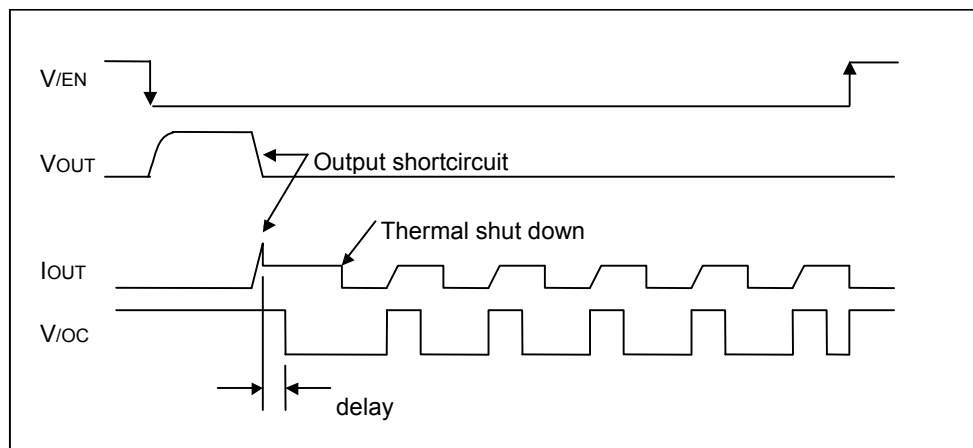


Fig.40 Over-current detection, thermal shutdown timing
(BD2062FJ)

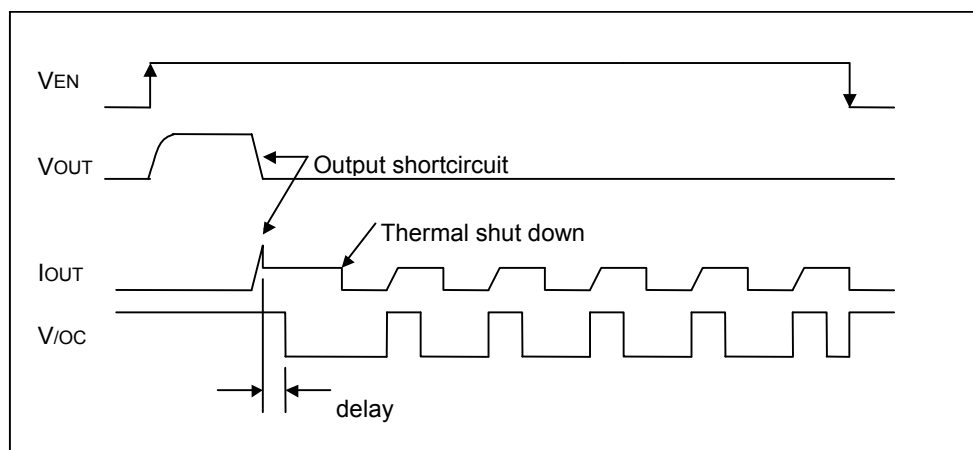


Fig.41 Over-current detection, thermal shutdown timing
(BD2066FJ)

●Typical Application Circuit

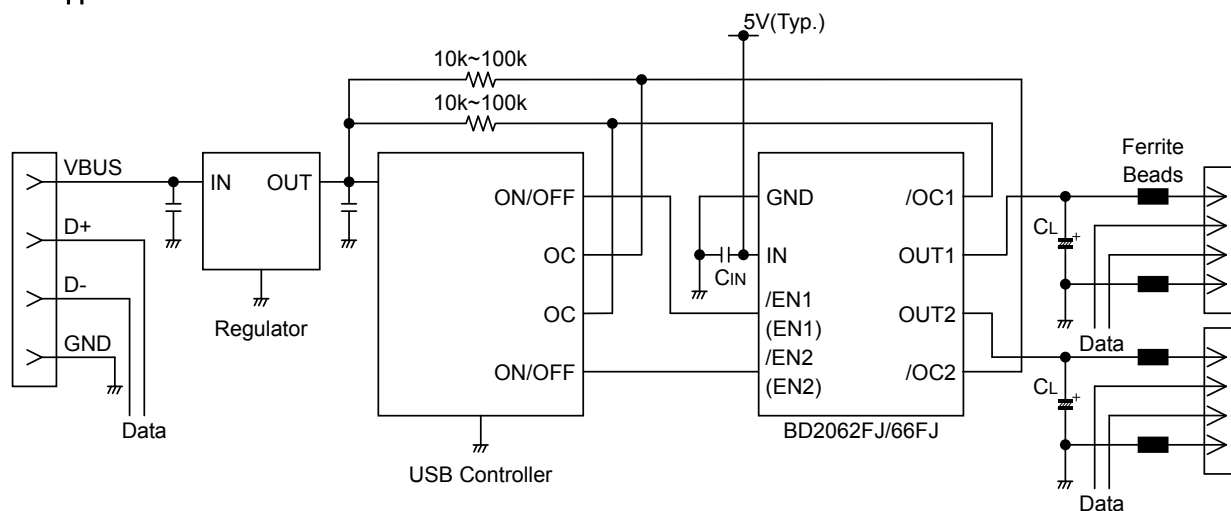


Fig.42 Typical application circuit

●Application Information

When excessive current flows owing to output shortcircuit or so, ringing occurs by inductance of power source line to IC, and may cause bad influences upon IC actions. In order to avoid this case, connect a bypass capacitor by IN terminal and GND terminal of IC. 1uF or higher is recommended.

Pull up /OC output by resistance 10kΩ ~ 100kΩ.

Set up value which satisfies the application as CL and Ferrite Beads.

This system connection diagram doesn't guarantee operating as the application.

The external circuit constant and so on is changed and it uses, in which there are adequate margins by taking into account external parts or dispersion of IC including not only static characteristics but also transient characteristics.

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The external circuit constant and so on is changed and it uses, in which there are adequate margins by taking into account external parts or dispersion of IC including not only static characteristics but also transient characteristics.

● Power Dissipation Character
(SOP-J8)

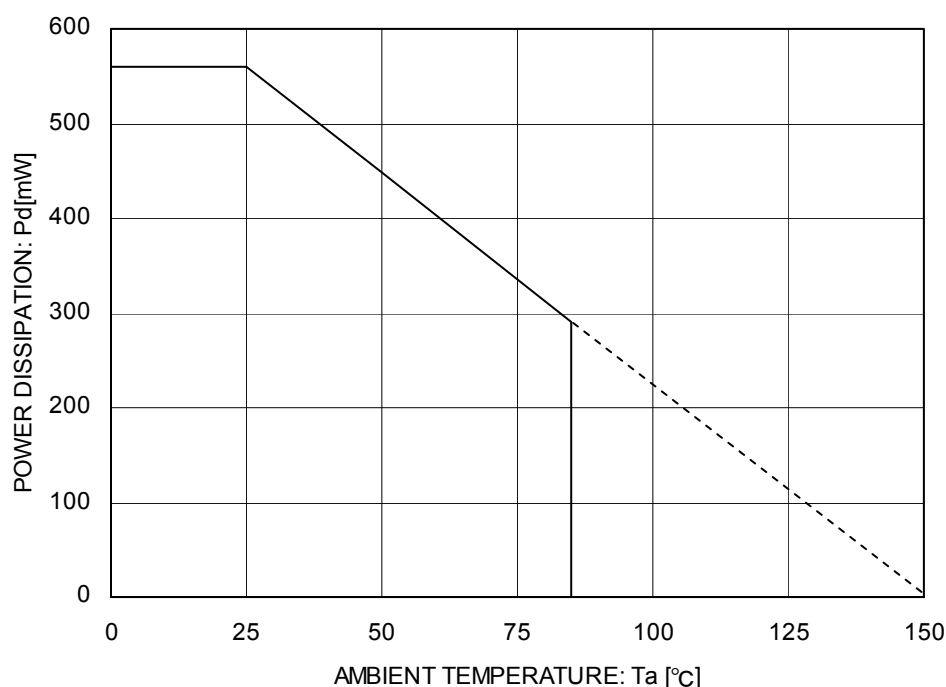


Fig.43 Power dissipation curve (Pd-Ta Curve)

● Notes for use

(1) Absolute Maximum Ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down devices, thus making impossible to identify breaking mode such as a short circuit or an open circuit. If any special mode exceeding the absolute maximum ratings is assumed, consideration should be given to take physical safety measures including the use of fuses, etc.

(2) Operating conditions

These conditions represent a range within which characteristics can be provided approximately as expected. The electrical characteristics are guaranteed under the conditions of each parameter.

(3) Reverse connection of power supply connector

The reverse connection of power supply connector can break down ICs. Take protective measures against the breakdown due to the reverse connection, such as mounting an external diode between the power supply and the IC's power supply terminal.

(4) Power supply line

Design PCB pattern to provide low impedance for the wiring between the power supply and the GND lines. In this regard, for the digital block power supply and the analog block power supply, even though these power supplies has the same level of potential, separate the power supply pattern for the digital block from that for the analog block, thus suppressing the diffraction of digital noises to the analog block power supply resulting from impedance common to the wiring patterns. For the GND line, give consideration to design the patterns in a similar manner.

Furthermore, for all power supply terminals to ICs, mount a capacitor between the power supply and the GND terminal. At the same time, in order to use an electrolytic capacitor, thoroughly check to be sure the characteristics of the capacitor to be used present no problem including the occurrence of capacity dropout at a low temperature, thus determining the constant.

(5) GND voltage

Make setting of the potential of the GND terminal so that it will be maintained at the minimum in any operating state. Furthermore, check to be sure no terminals are at a potential lower than the GND voltage including an actual electric transient.

(6) Short circuit between terminals and erroneous mounting

In order to mount ICs on a set PCB, pay thorough attention to the direction and offset of the ICs. Erroneous mounting can break down the ICs. Furthermore, if a short circuit occurs due to foreign matters entering between terminals or between the terminal and the power supply or the GND terminal, the ICs can break down.

- (7) Operation in strong electromagnetic field
Be noted that using ICs in the strong electromagnetic field can malfunction them.
- (8) Inspection with set PCB
On the inspection with the set PCB, if a capacitor is connected to a low-impedance IC terminal, the IC can suffer stress. Therefore, be sure to discharge from the set PCB by each process. Furthermore, in order to mount or dismount the set PCB to/from the jig for the inspection process, be sure to turn OFF the power supply and then mount the set PCB to the jig. After the completion of the inspection, be sure to turn OFF the power supply and then dismount it from the jig. In addition, for protection against static electricity, establish a ground for the assembly process and pay thorough attention to the transportation and the storage of the set PCB.
- (9) Input terminals
In terms of the construction of IC, parasitic elements are inevitably formed in relation to potential. The operation of the parasitic element can cause interference with circuit operation, thus resulting in a malfunction and then breakdown of the input terminal. Therefore, pay thorough attention not to handle the input terminals, such as to apply to the input terminals a voltage lower than the GND respectively, so that any parasitic element will operate. Furthermore, do not apply a voltage to the input terminals when no power supply voltage is applied to the IC. In addition, even if the power supply voltage is applied, apply to the input terminals a voltage lower than the power supply voltage or within the guaranteed value of electrical characteristics.
- (10) Ground wiring pattern
If small-signal GND and large-current GND are provided, It will be recommended to separate the large-current GND pattern from the small-signal GND pattern and establish a single ground at the reference point of the set PCB so that resistance to the wiring pattern and voltage fluctuations due to a large current will cause no fluctuations in voltages of the small-signal GND. Pay attention not to cause fluctuations in the GND wiring pattern of external parts as well.
- (11) External capacitor
In order to use a ceramic capacitor as the external capacitor, determine the constant with consideration given to a degradation in the nominal capacitance due to DC bias and changes in the capacitance due to temperature, etc.
- (12) Thermal shutdown circuit (TSD)
When junction temperatures become detected temperatures or higher, the thermal shutdown circuit operates and turns a switch OFF. The thermal shutdown circuit is aimed at isolating the LSI from thermal runaway as much as possible. Do not continuously use the LSI with this circuit operating or use the LSI assuming its operation.
- (13) Thermal design
Perform thermal design in which there are adequate margins by taking into account the power dissipation (P_d) in actual states of use.

●Ordering part number

B	D
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Part No.

2	0	6	2
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Part No.
2062
2066

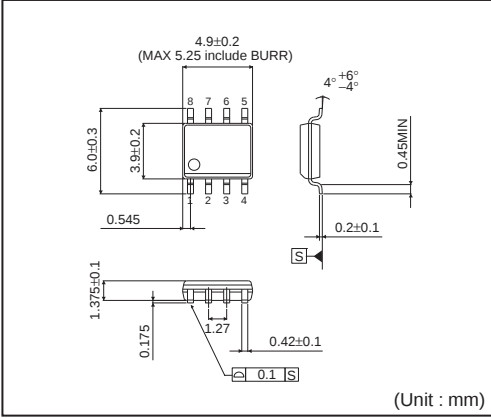
F	J
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Package
FJ: SOP-J8

E	2
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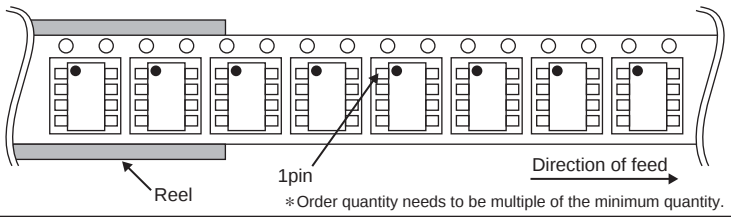
Packaging and forming specification
E2: Embossed tape and reel

SOP-J8



<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	2500pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



Notes

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